Markey ye.	ry film and a laws		Tirk ar and
	in the state of th		
2	cncapsulated) near2 thickness (((sealing adj resin) encapsulating encapsulated) near2 thickness) and (chi	USPAT	2000/11/30 13:4
	device die) 48 (((sealing adj resin) encapsulating	USPAT	2001/06/14 08:2
	encapsulated) near2 thickness) near5 (cludevice die) 4 (("5844168") or ("5642261") or ("552583")		2000/11/30 15:3
	or ("5683942")).PN. 0 (("4996587") or ("5672909") or	USPAT	2000/11/30 15:3
14	("5796170")).PN. 10 257/723	USPAT	2000/12/01 16:3
	42   257/724	USPAT	2000/12/01 16:3
	65 257/723 257/724	USPAT	2000/12/01 16:
8	81 (257/723 257/724) and lead and substrate	e USPAT	2000/12/01 16:3
1	39 ((257/723 257/724) and lead and substra- and multichip	te) USPAT	2000/12/01 16:
1	35 ((257/723 257/724) and lead and substra	te) USPAT	2000/12/01 16:4
)	and (chip nearl chip) 94 (((257/723 257/724) and load and	USPAT	2000/12/01 16:
	substrate) and (chip nearl chip)) not (((257/723 257/724) and lead and substrate) and multichip)		
	3 (multichip nearl package) and ((flexible near (substrate tape insulation)) with	e USPAT; EPO; JPO;	2001/06/14 08:3
	(conductive near trace))	DERWENT	
	81 (((sealing adj resin) encapsula\$4) near   thickness) near5 (chip device die)	2 USPAT	2001/06/14 08:
	(((sealing adj resin) encapsula\$4) near thickness) near5 (chip device die)	US-PGPUB;	2001/06/14 08:
	1 ((((sealing adj resin) encapsula\$4) nea thickness) near5 (chip device die)) and		2001/06/14 08:
	(flexible nearl (lead trace conductive) (multichip nearl package) and ((flexible near (substrate tape insulation)) with		2001/06/14 08:
	(conductive near trace)) 71   (second near1 chip) with (heat near2	DERWENT USPAT;	2002/05/14 13:
	(conducting releasing radiator sink))	US-PGPUB; EPO; JPO;	2002/03/14 13.
	(second near1 chip) with (heat near2 (conducting conductive release releasing		2002/05/14 15:
	radiator sink)) 1 6156980.URPN.	EPO; JPO; DERWENT USPAT	2002/05/14 13:
4	5 ("5352926"   "5710071"   "5777386"   "5969461"   "5973927").PN.	USPAT	2002/05/14 13:
	1 "5086431".PN.	USPAT	2002/05/14 14:
	2 5638391.URPN.	USPAT	2002/05/14 14:
	22 5323292.URPN.	USPAT	2002/05/14 14:
	40 ("3324224"   "4313492"   "4335781"	USPAT	2002/05/14 14:
	"4480262"   "4561040"   "4603374"		
	"4727455"   "4740866"   "4806503"     "4825284"   "4888449"   "4897508"		
	"4912548"   "4939316"   "4949219"		
	"4961106"   "4967260"   "5015803"		
	"5018005"   "5023398"   "5025114"		
1	"5055967"   "5066368"   "5073521"	}	
	"5103292"   "5175613"   "5184211"		
	"5189505"   "5214308"   "5216283"		
1	"5235209"   "5256205"   "5284706"	1	
	"5291064"   "5323292"   "5324569"     "5334857"   "5352926"   "5353193"	1	L
			111
	n n n n n n n		
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Search Wistory ( ) A Dr. C. H. H. AM ( Fig. 1) The TRIC LAST Wistory with a simple of thing of the Wistory beauty

	1	"4763188"   "4982265"   "5025306"	I	1	
		"5040052"   "5140404"   "5172215"	1		
- 11		"5176311"   "5177032"   "5198888"			
		"5291060"   "5291061"   "5323060"   "5384689"   "5432729"   "5620928"	1	1	
1.19		"5682062"   "5721452"   "5739581"			
1		"5815372"   "5872025"   "5886412"		1	
		"5989982"   "6013948"   "6030855"			
1		"RE36613"   "6033931"   "6049094"   "6051886"   "6057598"   "6087722"	1		
		"6133637"   "6201302"   "6204091"			
		"6215182"   "6229217").PN.	1		
	187	(second adj chip) and (heat near2	USPAT;	2002/05/14	15:0
- 4		<pre>(conducting conductive release releasing radiator sink))</pre>	US-PGPUB; EPO; JPO;		
			DERWENT		
	165	((second adj chip) and (heat near2	USPAT;	2002/05/14	15:0
		(conducting conductive release releasing	US-PGPUB; EPO; JPO;	1	
		radiator sink))) not ((second nearl chip) with (heat near2 (conducting conductive	DERWENT		
		release releasing radiator sink)))	1		
	112	(((second adj chip) and (heat near2	USPAT;	2002/05/14	15:5
		<pre>(conducting conductive release releasing radiator sink))) not ((second nearl chip)</pre>	US-PGPUB; EPO; JPO;	1	
		with (heat near2 (conducting conductive	DERWENT		
		release releasing radiator sink)))) and		1	
	2	(wire wiring)   ("5866949"   "5925934").PN.	110 D M	2002/05/14	15.0
	0	6201266.URPN.	USPAT USPAT	2002/05/14	
	16	5199165.URPN.	USPAT	2002/05/14	
	16	5199165.URPN.	USPAT	2002/05/14	
	13	("2350348"   "3361195"   "3564109" !   "4047198"   "4327399"   "4519447"	USPAT	2002/05/14	15:2
		"4631636"   "4727454"   "4859520"	1		
		"4878152"   "4967314"   "4994215"			
	27	"5095359").PN.	Паруш	2002/05/14	10.0
		4862322.URPN.   5438224.URPN.	USPAT USPAT	2002/05/14 2002/05/14	
	0	6313527.URPN.	USPAT	2002/05/14	
	2	("5438224"   "6072243").PN.	USPAT	2002/05/14	
	3 15	6137164.URPN. ("3577037"   "5347162"   "5438224"	USPAT USPAT	2002/05/14	
į	13	"5468681"   "5477160"   "5483421"	USPAI	2002/05/14	10:4
		"5759047"   "5786628"   "5815374"		1	
		"5918113"   "5958590"   "5965064"			
Ì	5.3	"5977640"   "5984691"   "6013948").PN. (((second adj chip) and (heat near2	USPAT;	2002/05/14	16.0
1	33	(conducting conductive release releasing	US-PGPUB;	2002/03/14	10.0
		radiator sink))) not ((second near1 chip)	EPO; JPO;		
		with (heat near2 (conducting conductive	DERWENT		
		release releasing radiator sink)))) not ((((second adj chip) and (heat near2			
		(conducting conductive release releasing			
		radiator sink))) not ((second near1 chip)			
1		with (heat near2 (conducting conductive		1	
		release releasing radiator sink)))) and (wire wiring))			
1	1570	noise near shield\$3	USPAT;	2002/05/14	16:0
			US-PGPUB;	1	
			EPO; JPO;		
1	0	257/685,686,723,724,777	USPAT;	2002/05/14	16:0
1			US-PGPUB;		
			FPO; TPO	1	
				:	. :
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	-	to the action of the property of the	**************************************		· : 14
			, 1 de 1 de 1997		
			EPO; JPO;		
			DERWENT	0000/05/14	16 07
_	4	("5677575"   "5757078"   "5821625"	USPAT	2002/05/14	16:07
		"5869903").PN.		0000/05/14	16.00
_	,	5821625.URPN.	USPAT	2002/05/14	
_	6		USPAT	2002/05/14	
_	5		USPAT	2002/05/14	10:11
	6	"5596225"   "5656856").PN. (noise near shield\$3) and ((chip ad;1	USPAT;	2002/05/14	16.10
_	1 0	chip) (dual adj dies adj packag\$3))	US-PGPUB;	2002/03/14	10.12
		Chip (dual ad) dies ad) packagys;	EPO; JPO;		
			DERWENT		
_	6	((noise near shield\$3) and ((chip adj1	USPAT;	2002/05/14	16.20
		chip) (dual adj dies adj packag\$3))) not	US-PGPUB;	2002/03/11	10.20
		((noise near shield\$3) and	EPO; JPO;		
		257/685,686,723,724,777.ccls.)	DERWENT		
_	5		USPAT;	2002/05/14	16.22
	3	(chip semiconductor (integrated adj	US-PGPUB;	2002/03/1	10.22
	1	circuit)))	EPO; JPO;	1	
			DERWENT		
	2	(alm (aluminum adj nitride)) near3 (solder	USPAT;	2002/05/28	13.58
	-	adj (bump ball))	US-PGPUB;	2002,00,20	
		ady (bump bally)	EPO; JPO;	1	
			DERWENT		
_	41	(aln (aluminum adj nitride)) near3 (bump	USPAT;	2002/05/28	13:59
		ball)	US-PGPUB;	2002,00,20	10.00
			EPO; JPO;		
	1		DERWENT	1	
_	8	((solder adj (bump ball)) near2 copper)	USPAT:	2002/05/29	10:10
		and ((wiring adj layer) near2 copper)	US-PGPUB;	2002,00,25	10.10
	1	and ((milling ad) layer, nearly copper,	EPO; JPO;		
			DERWENT		
_	1.3	(lead near2 copper) and ((wiring adj	USPAT;	2002/05/29	10:12
	1	layer) ncar2 copper)	US-PGPUB;	,,	
			EPO; JPO;		
			DERWENT		
-	21	(electrode near2 copper) and ((wiring adj	USPAT;	2002/05/29	10:12
		layer) near2 copper)	US-PGPUB;		
			EPO; JPO;		
			DERWENT		
-	60	"5477082"	USPAT;	2002/05/29	12:27
			US-PGPUB;		
			EPO; JPO;		
			DERWENT		
-	47	"5438224"	USPAT;	2002/05/29	12:27
			US-PGPUB;		
			EPO; JPO;		
			DERWENT		
	15	"4703483"	USPAT;	2002/05/29	12:32
	(		US-PGPUB;		
			EPO; JPO;		
			DERWENT		
	11	"5719436"	USPAT;	2002/05/29	1.2:34
			US-PGPUB;		
			EPO; JPO;		
	V		DERWENT		
	129	"5477082" "5438224" "4703483" "5719436"	USPAT;	2002/05/29	12:34
			US-PGPUB;		
			EPO; JPO;		
			DERWENT		
	7	("5065505"   "5396403"   "5477082"	USPAT	2002/05/29	12:39
		"5977640"   "6075287"   "6133637"	l.		
		"6150724").PN.			
	11	("5471369"   "5646829"   "5719436"	יוּעסטוו	2002/05/20	1 1 2 - 4 2

		The state of the s		
T.	T	"5205035"   "5208729"   "5238 <b>1</b> 76"	1	n i
		"5243141"   "5244833"   "5252857"	}	1
		"5268815").PN.		1
l _	6		USPAT	2002/05/29 13:02
_	í		USPAT	2002/10/10 09:17
_	4		USPAT	2002/10/10 09:17
		"5869903").PN.	1	
_	6	5821625.URPN.	USPAT	2002/10/10 09:18
-	5	("4763188"   "4811082"   "5508565"	USPAT	2002/10/10 09:18
		"5596225"   "5656856").PN.	1	1
_	32779	chip adj2 chip) (second adj1 chip	USPAT;	2002/10/10 09:47
			US-PGPUB;	1
			EPO; JPO;	1
1	1411		DERWENT	0000 (40 (40 00 50
-	70	(chip adj2 chip) (second adj1 chip) and	USPAT;	2002/10/10 09:52
	1	((digital analog) near cell)	US-PGPUB;	
			EPO; JPO; DERWENT	
	5	((chip adj2 chip) (second adj1 chip) and	USPAT;	2002/10/10 09:53
-	1	((digital analog) near cell)) and ((bond	US-PGPUB;	2002/10/10 09.55
	1	bonding) adj pad)	EPO; JPO;	
		boliding) day pady	DERWENT	1
_	3106	(digital analog) near1 cell	USPAT;	2002/10/10 09:38
	0200	(argrout analog) nourr ooli	US-PGPUB;	2002, 20, 20 03, 00
			EPO; JPO;	1
			DERWENT	
-	14	((digital analog) near cell) and (second	USPAT:	2002/10/10 09:45
Î		near1 (die chip))	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	8	1 ( )	USPAT;	2002/10/10 09:46
		nearl (die chip))	US-PGPUB;	
1			EPO; JPO;	
	41933	(abia manua abia) (assend manua (dia	DERWENT	2002/10/10 09:50
-	41933		USPAT; US-PGPUB;	2002/10/10 09:50
		chip))	EPO; JPO;	
	i		DERWENT	
l _	38050	(chip near2 chip) ((second adj (die chip))	USPAT;	2002/10/10 09:52
		(second adj1 (die chip)))	US-PGPUB;	
1		(	EPO; JPO;	
			DERWENT	
-	1529	((chip near2 chip) ((second adj (die	USPAT;	2002/10/10 09:53
		chip)) (second adjl (die chip)))) and	US-PGPUB;	
		digital and analog and cell	EPO; JPO;	1
	1		DERWENT	
-	215	(((chip near2 chip) ((second adj (die	USPAT;	2002/10/10 09:53
1		chip)) (second adjl (die chip)))) and	US-PGPUB;	1
	1 7	digital and analog and cell) and ((bond	EPO; JPO;	
1	179	bonding) adj pad)	DERWENT USPAT;	2002/10/10 09:54
[ -	1/9	((((chip near2 chip) ((second adj (die chip))) (second adj1 (die chip)))) and	US-PGPUB;	2002/10/10 09:54
		digital and analog and cell) and ((bond	EPO; JPO;	
1		bonding) adj pad)) and (wire wiring)	DERWENT	
_	177	(((((chip near2 chip) ((second adj (die	USPAT;	2002/10/10 09:55
	1	chip)) (second adjl (die chip)))) and	US-PGPUB;	2002, 20, 20
		digital and analog and cell) and ((bond	EPO; JPO;	
		bonding) adj pad)) and (wire wiring)) and	DERWENT	
	A	circuit		
-	120	(((((chip near2 chip) ((second adj (die	USPAT;	2002/10/10 09:55
		chip)) (second adjl (die chip)))) and	US-PGPUB;	
	1	digital and analog and cell) and ((bond	EPO; JPO;	
		bonding) adj pad)) and (wire wiring)) and	DERWENT	
I		circuit) and dram	** *:	
				•

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	•	٠	The transfer of the constant of the terms of		
1			"3778886"   "3813650"   "3813773"   "3983619"   "3999105"   "4300153"		
			"4387503"   "4426773"   "4525921"   "4598462"   "4612083"   "4613891"   "4646128"   "4659931"   "4672737"		
			"4677528"   "4703170"   "4706166"   "4761681"   "4764846"   "4783695"		
ł			"4801992"   "4803595"   "4807021"   "4827327"   "4862249"   "4894706"   "4897708"   "4901136"   "4907128"		
			"4939568"   "4941033"   "4954875"     "4956694"   "4956695"   "4956746"     "4959749"   "4983533"   "4989063"		
			"4996583"   "5006923"   "5013687"   "5019943"   "5025306"   "5028986"		
			"5032896"   "5055425"   "5075253"   "5093708"   "5104820"   "5111278"   "5117282"   "5128831"   "5135556"		
			"5138437"   "5138438"   "5172303"     "5191404"   "5191405"   "5198888"     "5200300"   "5202754"   "5221642"		
	10		"5222014"   "5229647"   "5231304"   "5247423"   "5259110"   "5270261"   "5270571"   "5279029"   "5279984"		
			"5283107"   "5311401"   "5330359"   "5377077"   "5420751"   "5446620"	T	
			"5455740"   "5475920"   "5479318"   "5493476"   "5499160"   "5502333"   "5532614"   "5543664"   "5550711"		
_		13	"5552963"   "5561591"   "5566051"     "5827759"   "5844296"   "5853603").I   ("4724427"   "4857893"   "5023624"		2002/10/10 10:25
1			"5202752"   "5345231"   "5717231"   "5764655"   "5929825"   "5999409"   "6096496"   "6161205"   "6181001"		
_		12	"6201296").PN. "6054337"	USPAT;	2002/10/10 13:05
				US-PGPUB; EPO; JPO; DERWENT	
Ī		4	"5894166"	USPAT; US-PGPUB; EPO; JPO;	2002/10/10 13:05
-		17	"5898223"	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 13:05
-		10	"6147401"	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 13:05
-		2	"6414396"	DERWENT USPAT; US-PGPUB; EPO; JPO;	
-		41	"6054337" "5894166" "5898223" "61474 "6414396"	US-PGPUB; EPO; JPO;	2002/10/10 13:06
-		0 10	6355977.URPN. ("5757179"   "5834844"   "5898223" "5903044"   "5960308"   "5976953"   "5977641"   "6002163"   "6005262"	DERWENT USPAT USPAT	2002/10/10 13:09 2002/10/10 13:09

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Y .	and the second of the second o		
	"5923091"   "5946545"   "5995379"		
18	"6057598").PN. 6057598.URPN.	USPAT	2002/10/10 13:
8	("5294826"   "5341979"   "5367765"   "5506756"   "5532512"   "5610442"   "5724230"   "5786635").PN.	USPAT	2002/10/10 13:3
10	"5784230"   "5786633"   "5717245"   "5783870"   "5894166"   "5923090"   "5923091"   "5946545"   "5995379"	USPAT	2002/10/10 13:3
	"6057598").PN.		
6	6255736.URPN. ("4764804"   "5034345"   "5480834"   "5534465"   "5585282"   "5726500").PN.	USPAT USPAT	2002/10/10 13:3 2002/10/10 13:3
3106	(digital analog) near cell	USPAT; US-PGPUB; EPO; JPO;	2002/10/10 13:
21	((digital analog) near cell) near3 (chip dram)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 13:
48	((digital logic) near cell) with (analog near cell)	DERWENT USPAT; US-PGPUB;	2002/10/10 14:3
5	(((digital logic) near cell) with (analog near cell)) with (chip dram)	EPO; JPO; DERWENT USPAT; US-PGPUB;	2002/10/10 14:2
	6460172.URPN.	EPO; JPO; DERWENT USPAT	2002/10/10 13:4
	("4402044"   "5197016"   "5361373"   "5384275"   "5402358"   "5425036" ! "5438681"   "5581742"   "5959871"	USPAT	2002/10/10 13:
9138	"6006022"   "6014509").PN. (multichip adj module) mcm	USPAT; US-PGPUB; EPO; JPO;	2002/10/10 14:-
25628	(digital logic input output analog) near cell	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 14:
104	((multichip adj module) mcm) and ((digital logic input output analog) near cell)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 14:
103	(((multichip adj module) mcm) and ((digital logic input output analog) near	DERWENT USPAT; US-PGPUB;	2002/10/10 14:
43	cell)) not ("6054337" "5894166" "5898223" "6147401" "6414396") ((((multichip adj module) mcm) and ((digital logic input output analog) near cell)) not ("6054337" "5894166" "5898223" "6147401" "6414396")) and (wire wiring)	EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:3
7794	and pad (digital logic analog) nearl cell	USPAT; US-PGPUB;	2002/10/10 14:4
14778	(multichip adj module) mcm (second nearl chip)	EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/10/10 16:0
106	((digital logic analog) near1 cell) and	DERWENT	2002/10/10 14.5

Where Hall symmetric is a regime  $\Delta M_{\rm c} = 4.5 \, \rm keV$  . The constant of the Art (  $1.00 \, \rm keV$  ) where  $1.00 \, \rm keV$  is the constant of the constant

a-	The state of the second	innar,	1: .
	chip))) not (((multichip adj module) mcm) and ((digital logic input output analog)	EPO; JPO; DERWENT	
- 73	near cell)) (((digital logic analog) nearl cell) and ((multichip adj module) mcm (second nearl chip))) and (ram dram)	USPAT; US-PGPUB; EPO; JPO;	2002/10/10 15:29
- 36	((((digital logic analog) nearl cell) and ((multichip adj module) mcm (second nearl chip))) and (ram dram)) not (((digital logic analog) nearl cell) and ((multichip adj module) mcm (second nearl chip))) not (((multichip adj module) mcm) and ((digital logic input output analog) near cell)))	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 15:28
- 48	(US-6137164-\$ or US-5793115-\$ or US-4862322-\$ or US-6344683-\$ or US-6156980-\$ or US-5533256-\$ or US-5638391-\$ or US-5323292-\$ or US-6052284-\$ or US-5608610-\$ or US-5578869-\$ or US-6201302-\$ or US-6340842-\$ or US-6201302-\$ or US-6225688-\$ or US-6201266-\$ or US-5199165-\$ or US-4774632-\$ or US-6292366-\$ or US-6069025-\$ or	USPAT; US-PGPUB	2002/10/10 15:3
	US-5539250-\$ or US-5438224-\$ or US-6313527-\$ or US-6080931-\$ or US-6072243-\$ or US-6232668-\$).did. or (US-5821625-\$ or US-6285076-\$ or US-6020867-\$ or US-5668040-\$ or US-6376917-\$ or US-6316822-\$ or US-5719436-\$ or US-6373447-\$ or US-6433398-\$ or US-6373447-\$ or US-6356958-\$ or US-6308143-\$ or US-6255736-\$ or US-6057598-\$ or US-5386623-\$ or US-5243208-\$ or US-6202183-\$ or US-6460172-\$).did. or (US-20020033526-\$ or US-20020130342-\$ or		
- 13	US-20020078278-\$ or US-20020006054-\$).did. ("4484292"   "5222293"   "5249134"   "5251147"   "5267176"   "5381343"   !"5471398"   "5481473"   "5613102"   "5638293"   "5666288"   "5712794"   "5901066").PN.	USPAT	2002/10/10 15:3
7 1 32	5793115.URPN. 6208545.URPN.	USPAT USPAT USPAT	2002/10/10 15:4 2002/10/10 15:4 2002/10/10 15:4
14778	((multichip adj module) mcm) (second nearl chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:09
59	(circuit adj area) near3 ((bond bonding) adj pad)	USPAT; US-PGPUB; FPO; TPO;	2002/10/10 16:10
•	ent enter ente	is a accident to a control of the graph of the control of the graph of the graph control of the graph of the	

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		na villa samaniania nina valan Samesa sama		1.1
		((bond bonding) adj pad))	EPO; JPO; DERWENT	
-	2	((circuit adj area) near3 ((bond bonding) adj pad)) and ((((multichip adj module)	USPAT; US-PGPUB;	2002/10/10 16:11
		mcm) (second near1 chip)) and (mother adj	EPO; JPO;	
1		chip))	DERWENT	
-	26	(((multichip adj module) mcm) (second	USPAT;	2002/10/10 16:12
		nearl chip)) and (mother adj chip)	US-PGPUB;	}
	1		EPO; JPO; DERWENT	
_	0	20020017718.URPN.	USPAT	2002/10/10 16:13
-	6	("4697095"   "5440423"   "5640107"	USPAT	2002/10/10 16:14
		"5801547"   "5977640"   "6049222").PN.	11	,,
-	24	4697095.URPN.	USPAT	2002/10/10 16:16
-	5	5446309.URPN.	USPAT	2002/10/10 16:20
-	3	("4697095"   "4890077"   "5008736").PN.	USPAT	2002/10/10 16:21
-	9	("4055754"   "4071902"   "4103182"	USPAT	2002/10/10 16:21
		"4350906"   "4446390"   "4509008"		1
1	23	"4550289"   "4558447"   "4612499").PN.	HODAM	2002/10/10 16 22
-	23	("5072364"   "5142634"   "5230068"   "5287467"   "5303356"   "5394529"	USPAT	2002/10/10 16:22
		"5428786"   "5454117"   "5469551"		
		"5508556"   "5564118"   "5592634"		
		"5623614"   "5630157"   "5732278"		
		"5760478"   "5834835"   "5856937"	1	
}		"5903908"   "5939782"   "5977640"	1	13
l		"5994166"   "6031284").PN.		